

Title (en)

SYSTEM AND METHOD FOR IMPROVED ELECTRONIC COMPONENT INTERCONNECTIONS

Title (de)

SYSTEM UND VERFAHREN FÜR VERBESSERTE ELEKTRONISCHE KOMPONENTENVERBINDUNGEN

Title (fr)

SYSTÈME ET PROCÉDÉ D'INTERCONNEXIONS AMÉLIORÉES DE COMPOSANTS ÉLECTRONIQUES

Publication

EP 3711463 A1 20200923 (EN)

Application

EP 18827292 A 20181115

Priority

- US 201762586815 P 20171115
- US 2018061395 W 20181115

Abstract (en)

[origin: WO2019099754A1] Systems and methods for improved interconnections for electronic components using ACAs are provided. The methods involve using magnets specific for each component to be connected and optimized in terms of size and strength and position relative to the substrate and component. Also provided are ovens adapted for use with the methods and systems and kits providing the parts of the system for use with existing ovens.

IPC 8 full level

H05K 3/32 (2006.01); **H05K 3/00** (2006.01); **H05K 13/00** (2006.01)

CPC (source: EP KR)

H05K 3/323 (2013.01 - EP KR); **H05K 3/0008** (2013.01 - EP KR); **H05K 2203/0165** (2013.01 - EP KR); **H05K 2203/0169** (2013.01 - EP KR); **H05K 2203/104** (2013.01 - EP KR)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

WO 2019099754 A1 20190523; AU 2018368939 A1 20200625; AU 2018368939 B2 20230831; AU 2023274124 A1 20231221; CA 3082894 A1 20190523; CN 111512708 A 20200807; EP 3711463 A1 20200923; JP 2021503186 A 20210204; JP 2023025166 A 20230221; JP 7193168 B2 20221220; JP 7440120 B2 20240228; KR 102668129 B1 20240523; KR 20200111162 A 20200928; KR 20240074921 A 20240528; SG 11202004250R A 20200629

DOCDB simple family (application)

US 2018061395 W 20181115; AU 2018368939 A 20181115; AU 2023274124 A 20231129; CA 3082894 A 20181115; CN 201880073739 A 20181115; EP 18827292 A 20181115; JP 2020545040 A 20181115; JP 2022193064 A 20221201; KR 20207017125 A 20181115; KR 20247016408 A 20181115; SG 11202004250R A 20181115